

## **SP F - IAP experiments. Boron plasma coatings and boronization studies.**

### **Plasma coatings – plasma parameters vs. film properties**

**C. Porosnicu, P. Dinca, B. Butoi, O. G. Pompilian, C. Staicu, B. Solomonea, C. P. Lungu**

### **Approaches for surface coating with Boron by PECVD at low and high deposition rates using diborane as precursor**

**S. Vizireanu, G. Dinescu, D. Stoica, T. Acsente, V. Satulu, G. Dinescu, F. Dumitrache, Marius Dumitru, G. Morjan**



## **Plasma coatings – plasma parameters vs. film properties**

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***IAP-Romania***



# Outline

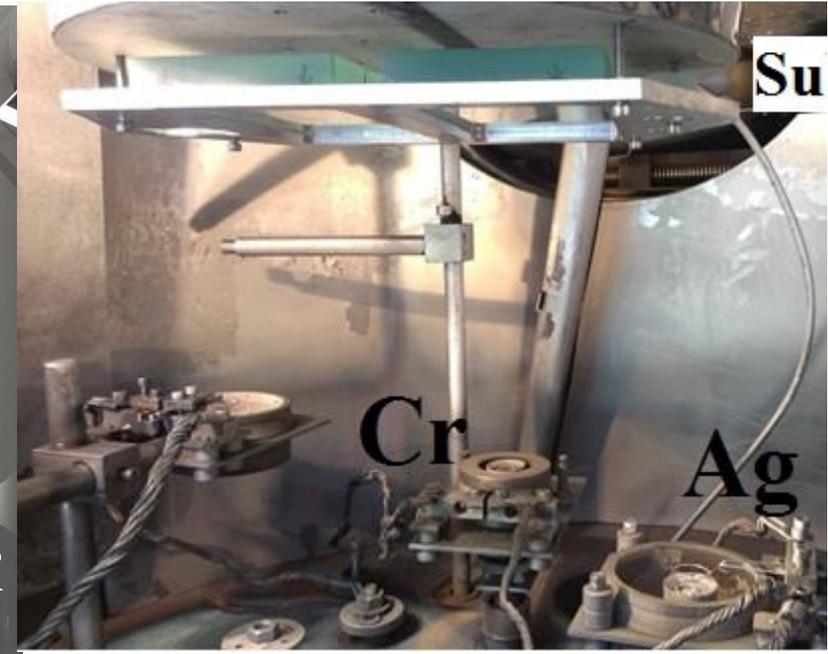
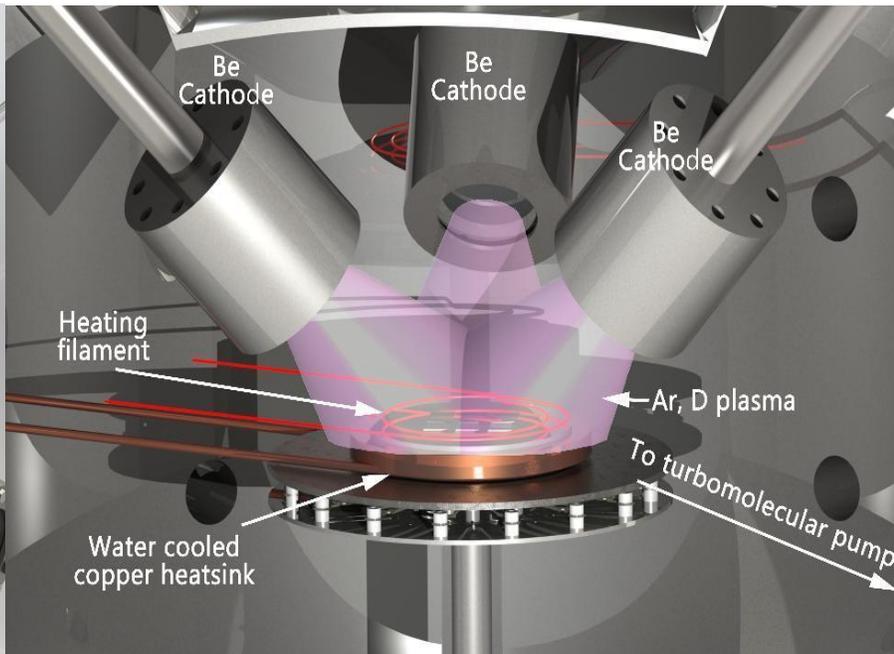
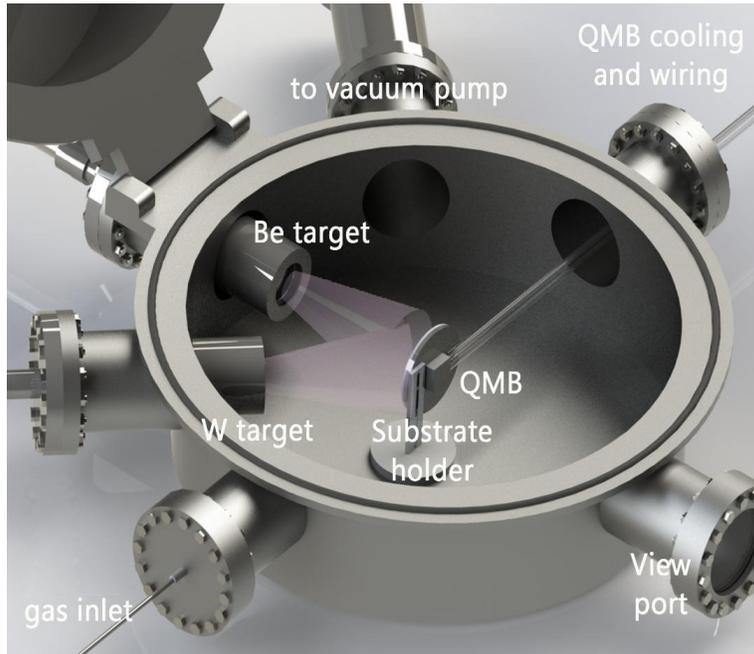


- 1. Boron coatings capabilities**
- 2. Coating setups: TVA, HiPIMS, RF MS**
- 3. Results form the B layers production task in 2025 under SBP4**
- 4. Plasma characterisation - ion energy measurements**
- 5. Prospects for studying B layers under SPF. Proposal of an experimental plan**

# From Be/D to B/D coating process – setups available



All the setups and experience used for Be was redirected to B



*Schematic description of the coating system used for B-D (Ne, N, He) layer deposition*

*Deposition system used for obtaining B (-W)-D/H/etc. layers*

*TVA Deposition system used for obtaining B (/W). layers*

**2024 was dedicated in setup and coating recipe development and plasma characterisation methods**



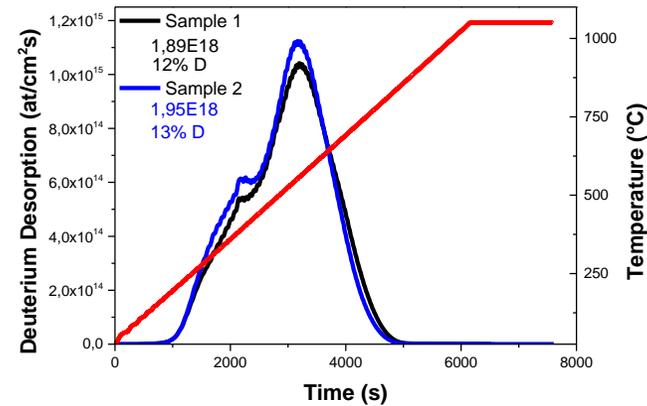
## Pre-deposition. Calibration

### Coating parameters

- 4x Si substrates
- 2 RF sources operated at 100W each
- Working pressure:  $1 \times 10^{-2}$  mbar
- Ar flow= 20sccm
- D<sub>2</sub> flow= 20 sccm



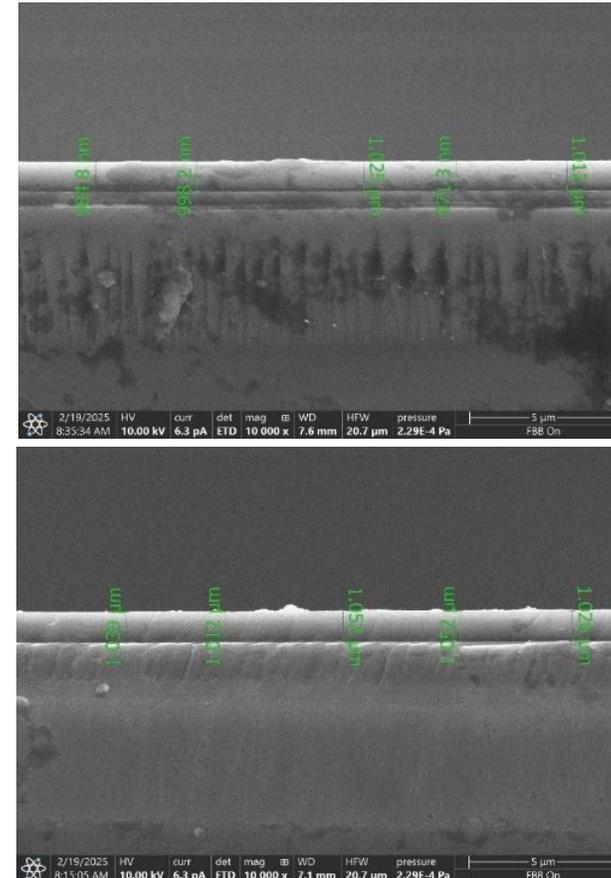
In situ photo of the deposition



TDS results (D concentration and quantity)

### Measurements

- SEM cross-section
- TDS



Cross-section-SEM results

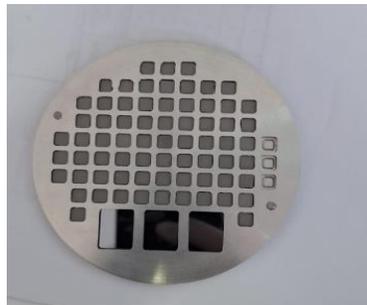
# Results form the B layers production taskin 2025 under SBP4



Boron+D<sub>2</sub>(10%) 5μm

Preparation of 5x5 mm<sup>2</sup> W samples coated with B+D<sub>2</sub>(10%)  
Subject to thermal treatment post-coating

- 60 tungsten substrates 5x5 mm
- 2 RF sources operated at 100W each
- Working pressure: 1x10<sup>-2</sup>mbar
- Ar flow= 20sccm
- D<sub>2</sub> flow= 20 sccm



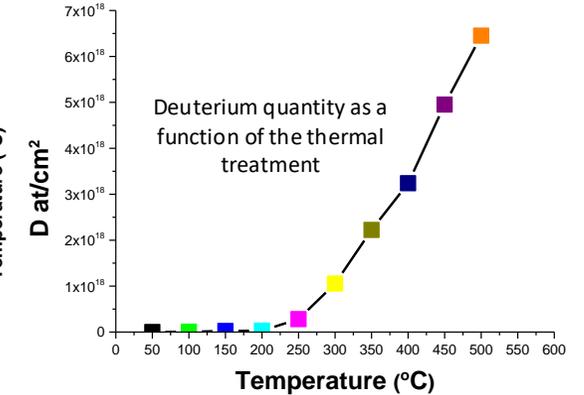
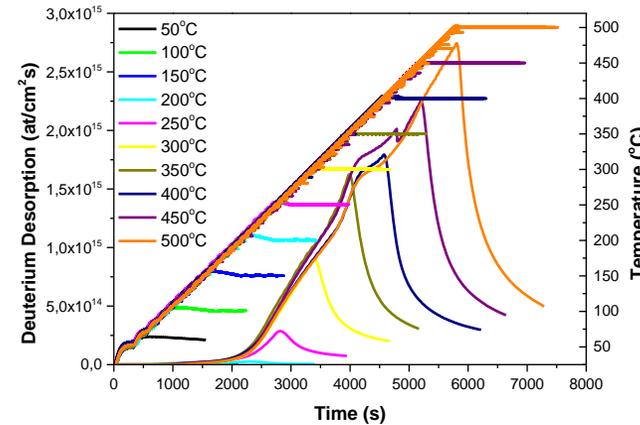
Sample holder



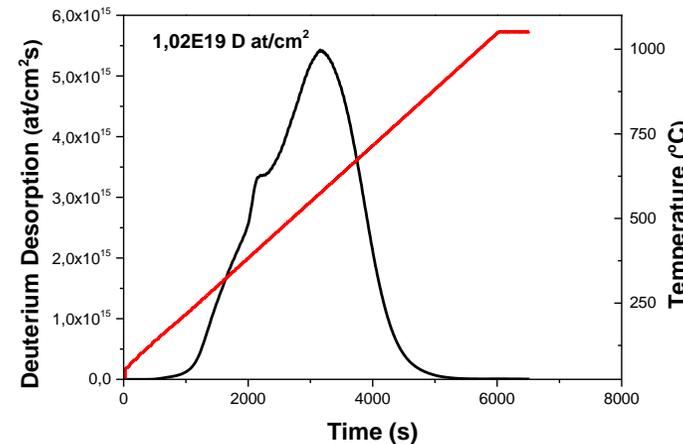
In situ photo of the deposition

Thermal Treatment- 50°C- 500°C\_Ramp 5°C/min

TDS measurement during Thermal Treatment



TDS result on B+D<sub>2</sub>\_1050°C



Temperature (°C)	D released (at/cm <sup>2</sup> )	D released during the TT (%)
50	7.45E+14	0.01
100	8.25E+15	0.08
150	2.21E+16	0.22
200	2.98E+16	0.29
250	2.82E+17	2.76
300	1.06E+18	10.39
350	2.22E+18	21.76
400	3.24E+18	31.76
450	4.95E+18	48.53
500	6.45E+18	63.24
1050	1.02E+19	100.00

# Results form the B layers production taskin 2025 under SBP4



## Boron deposition (100nm)

- 12 tungsten substrates 10x10 mm
- 2 RF sources operated at 100W each
- Working pressure:  $1 \times 10^{-2}$  mbar
- Ar flow= 20sccm
- D<sub>2</sub> flow= 20 sccm



In situ photo of the deposition



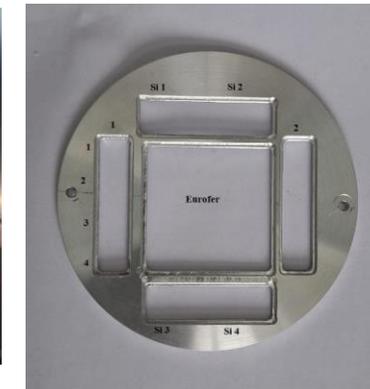
Sample holder

## Boron deposition (5µm) with and without D

- 8 tungsten substrates
- Eurofer  $\phi$  40 mm
- 2 RF sources operated at 100W each
- Working pressure:  $1 \times 10^{-2}$  mbar
- Ar flow= 20sccm
- D<sub>2</sub> flow= 20 sccm



In situ photo of the deposition



Sample holder

All samples were stable after the deposition (kept in vacuum).

Analisis (TDS, XRD,SEM, etc.) will be performed in April at IAP.

Samples to be sent this week (24-28 March) to the laboratories - sealed bags in vacuum, according to the matrix.

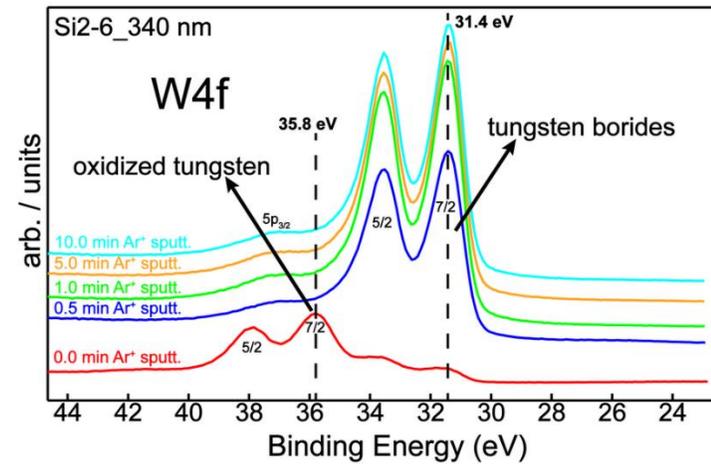
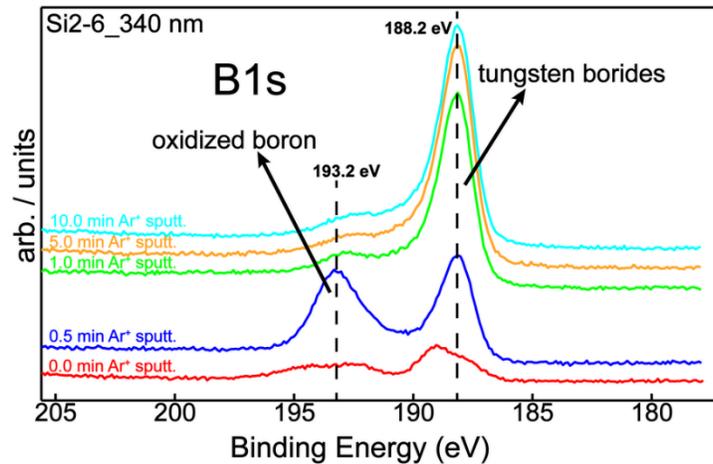
# XPS on tungsten-boride formation



Request for tungsten boride layers from Penn State University (A. Marin) under a PSU - WEST collaboration.

## **Samples coated by TVA – task performed.**

TVA parameters variation- W/B coatings with and without boride formation



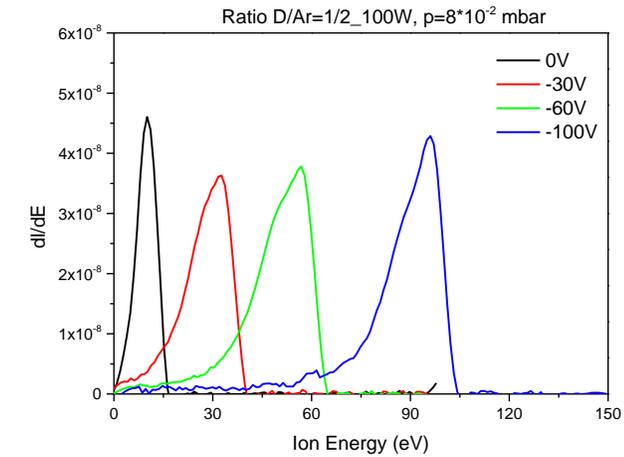
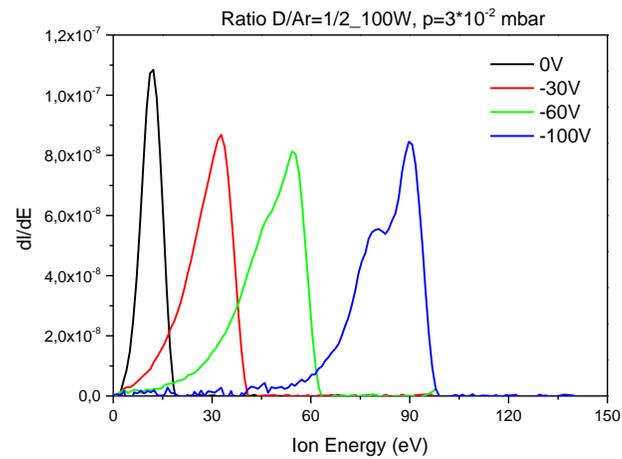
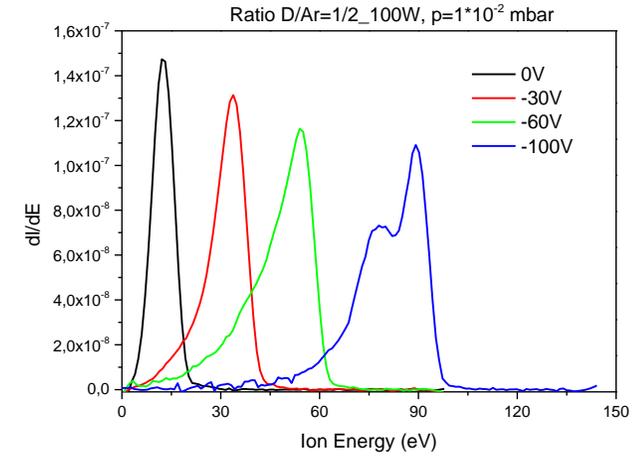
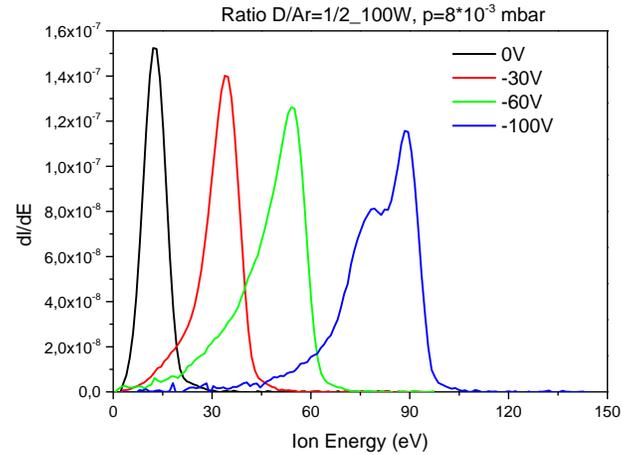
Elemental relative concentrations (at. %)

Si2-6_340 nm	B1s	C1s	O1s	W4f	B/W
0.0 min sputtering	15.1	45.3	32.9	6.7	2.3
0.5 min sputtering	45.9	-	38.8	15.3	3.0
1.0 min sputtering	58.3	-	15.8	25.9	2.3
5.0 min sputtering	63.0	-	13.5	23.5	2.7
10.0 min sputtering	63.3	-	13.1	23.6	2.7

# Plasma characterisation - Ion energy measurements



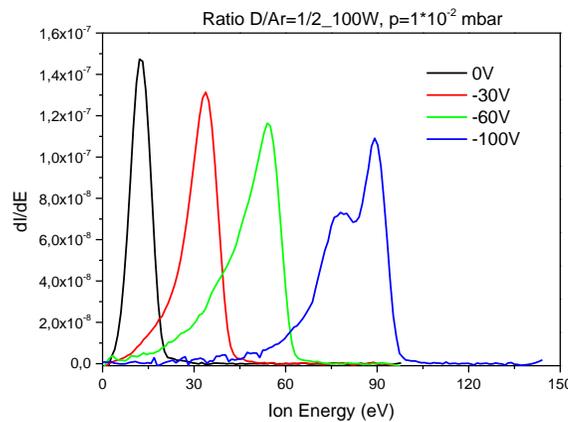
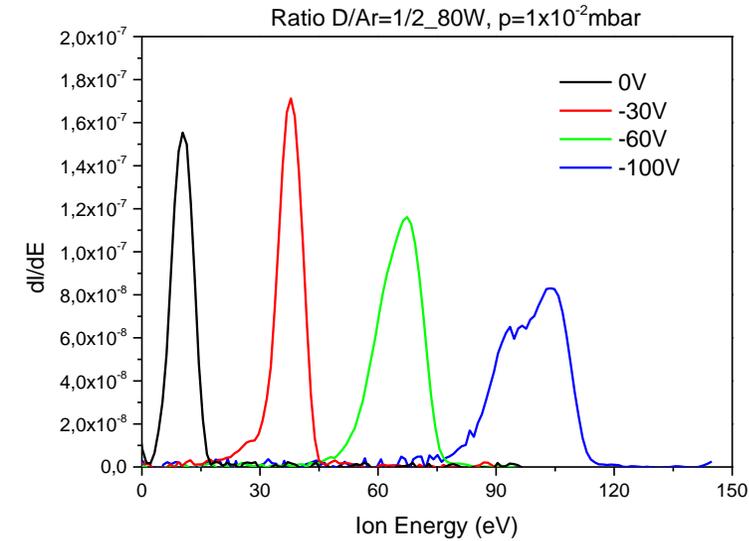
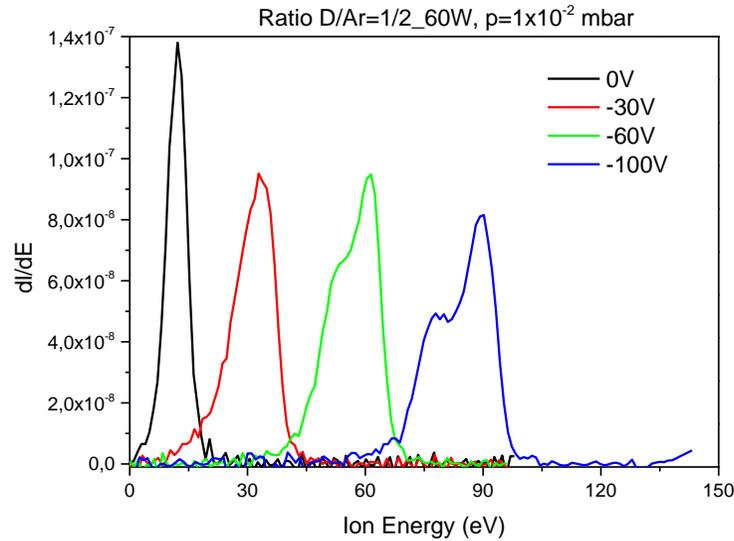
## RF plasma, P= 100W BIAS voltage influence – several pressures



# Plasma characterisation - Ion energy measurements



RF plasma,  $P= 1e-02$  mbar  
BIAS voltage influence – several RF Powers

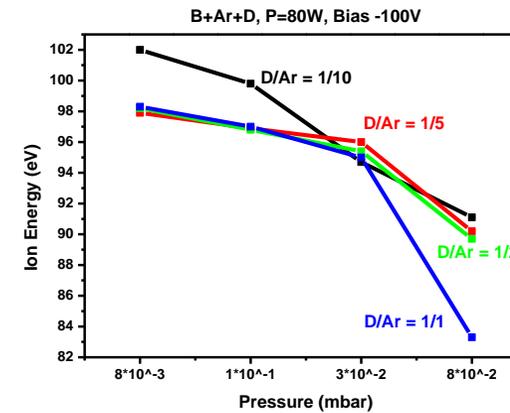
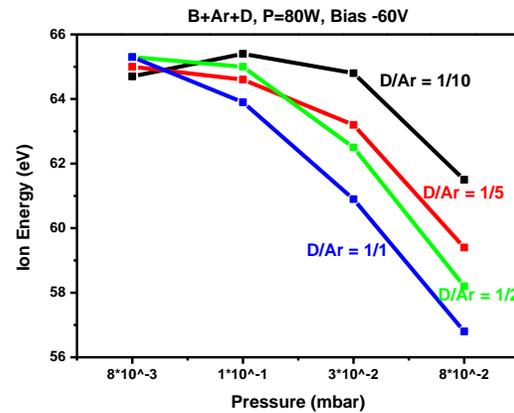
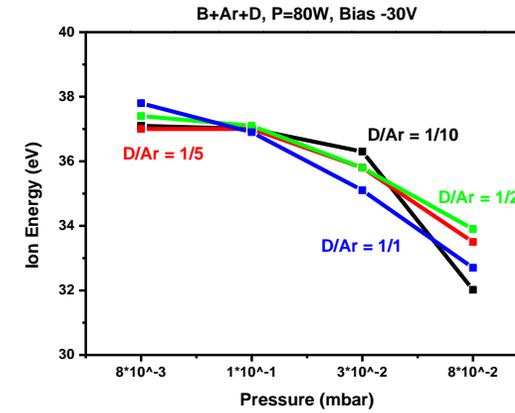
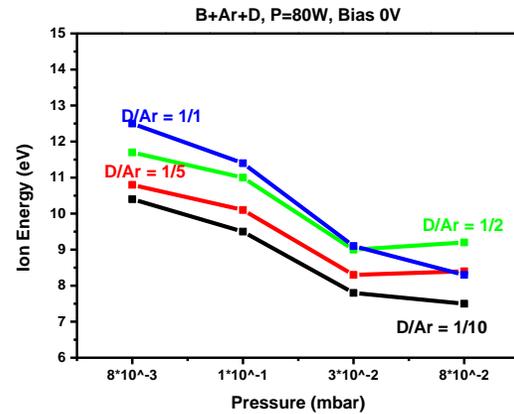


# Plasma characterisation - Ion energy measurements



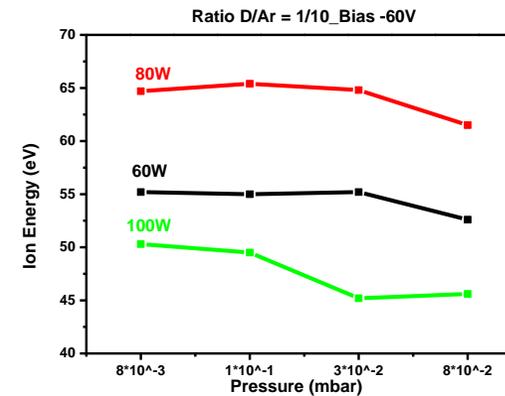
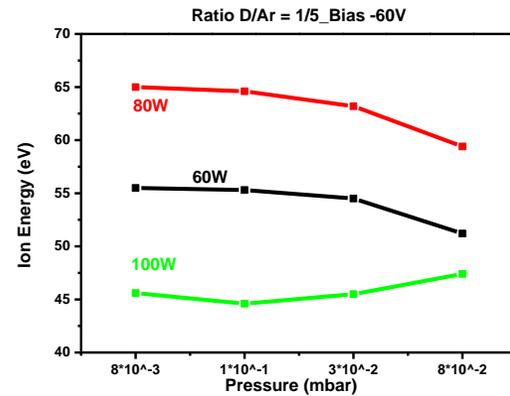
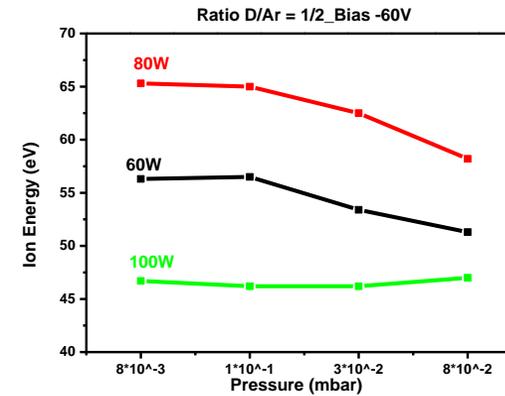
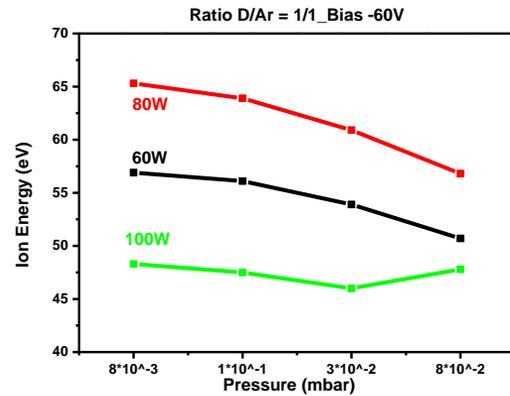
## RF plasma, Ion energy overview

### BIAS, pressure and D/Ar ratio

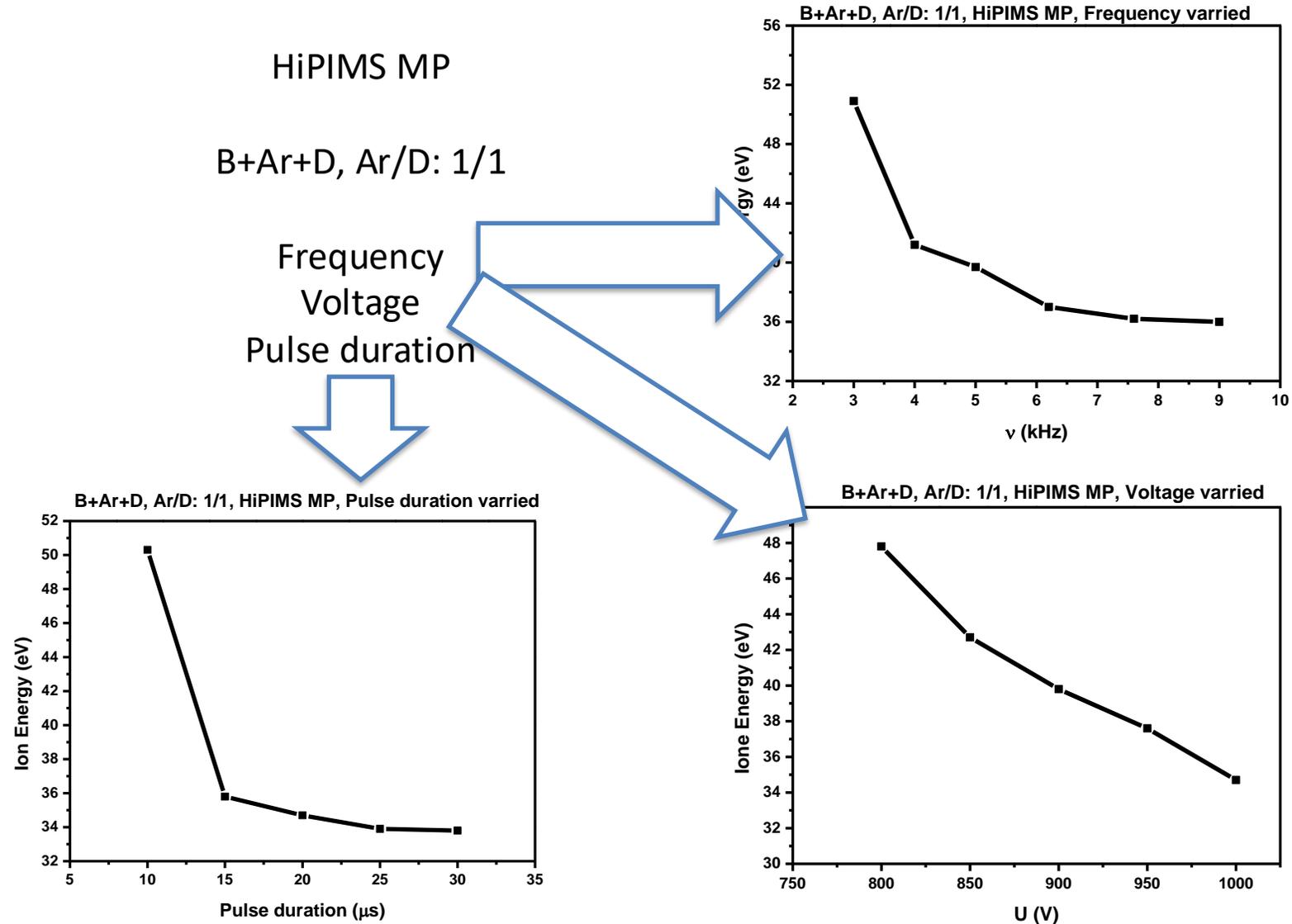




## RF plasma, Ion energy overview RF power, pressure and D/Ar ratio



# Plasma characterisation - Ion energy measurements

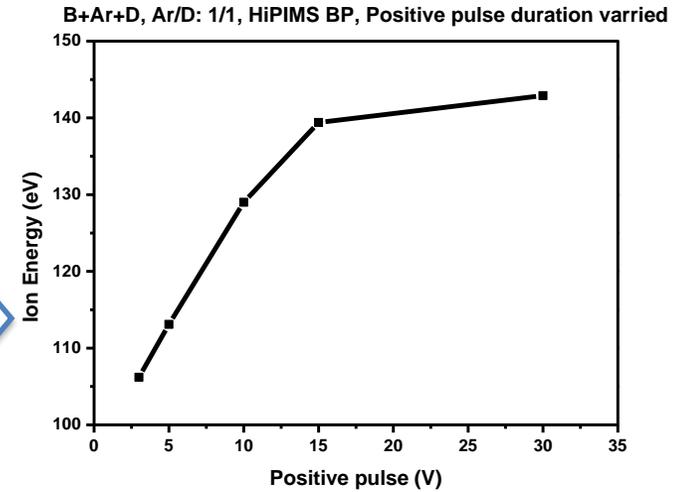


# Plasma characterisation - Ion energy measurements

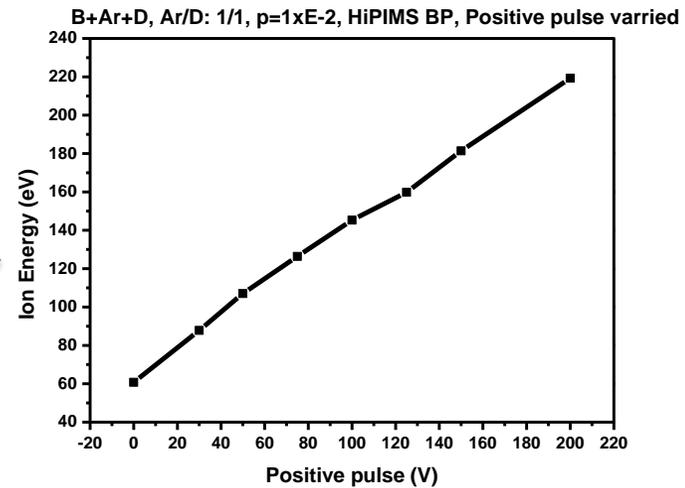
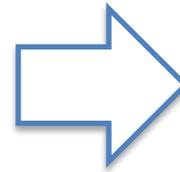


B+Ar+D, Ar/D: 1/1,  
Bipolar HiPIMS,

Positive pulse duration varied



Positive pulse voltage varied





# Prospects for studying B layers under SPF

## Proposal of an experimental plan - Example and ideas:

Different approach than under SPB: Focus on plasma parameters instead of coating properties.

<b><i>Parameters to be varied:</i></b>	
RF-MS parameters (Input power)	Pressure (1e-03 – 1e-01 mbar)
HiPIMS MP and BP plasma parameters (Pulse duration and frequency, voltage for negative and positive pulse)	Acceleration voltage  (0 to -200V for MS; -700V for TVA),
TVA parameters (voltage and current)	D/Ar ratio (1/20 – 1/1)

For each set of parameters, very well defined plasma characterization  
Ionisation degree (Langmuir probe), Ion energy (IEDF), species identification (MS, OES), etc.

### **Sistematic study**

Fixed plasma parameters – well characterized plasma => what will we obtain??  
stability, morphology, composition, adhesion, hardness, fuel retention

Work plan has to be established by SP Leaders under SPB, SPC, SP D, SPX and SPF since the need of a “*database of artificial B layers for physics studies: stability, fuel content, and release*”

# **Approaches for surface coating with Boron by PECVD at low and high deposition rates using diborane as precursor**

**S. Vizireanu**, D. Stoica, T. Acsente, V. Satulu, G. Dinescu, F. Dumitrache, Marius Dumitru, G. Morjan

***IAP-Romania***





# Outline

- **Experimental capabilities at INFLPR for plasma and laser CVD in diborane;**
  - PECVD configurations used for boron deposition;
  - Laser pyrolysis configuration used for preparation of B based nanoparticles;
- **Experimental parameters and sample labelling;**
- **Results on Glow discharge (GD-) samples: Surface morphology;**
- **Results on Plasma jet (J-) samples: Surface morphology;**
- **Time stability of boron samples on Si substrates;**
- **Boron samples deposited on W substrates;**
- **Boron samples deposited for various temperatures;**
- **Boron samples composition- XPS investigation;**
- **Conclusions and future plans.**

# Experimental capability at INFLPR for a boronization in diborane



**Advantages:** PECVD boron samples can be similar to those used in tokamak walls after boronization

**Drawback:** difficulties in diborane manipulation

**Caution!!!**



**High toxicity:** needs special health and safety equipment.

- TLV (Threshold Limit Values) = **0.1 ppm**;
- immediately dangerous at 40 ppm.

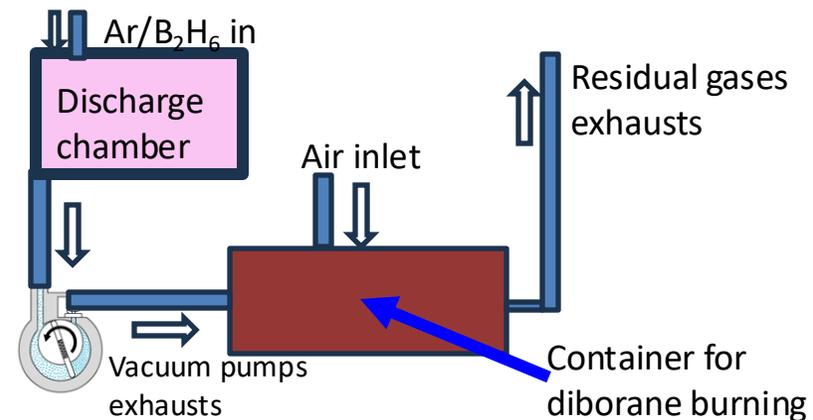
**Flammable gas:** auto ignition in air at temperature ~ 40°C.

**Special procedures must be followed to prevent hazard.**

## Details for handling diborane B<sub>2</sub>H<sub>6</sub>

- We used a mixture of B<sub>2</sub>H<sub>6</sub>/H<sub>2</sub> at ratio 1/10 in vacuum;
- **Non-used B<sub>2</sub>H<sub>6</sub> is burning** before exhausting;
- Dedicated mass-flow controllers;
- Diborane detection sensors.
- More safety measure must be implemented

**One essential component of the deposition system** is the container in which we burn the flammable gas. At INFLPR this container was used before for burning silane SiH<sub>4</sub> and lately for B<sub>2</sub>H<sub>6</sub> for boron doping by laser pyrolysis [1].



[1]. Balas M.; Dumitrache F. et al, Nanomaterials 2018, 8, 495  
<https://doi.org/10.3390/nano8070495>



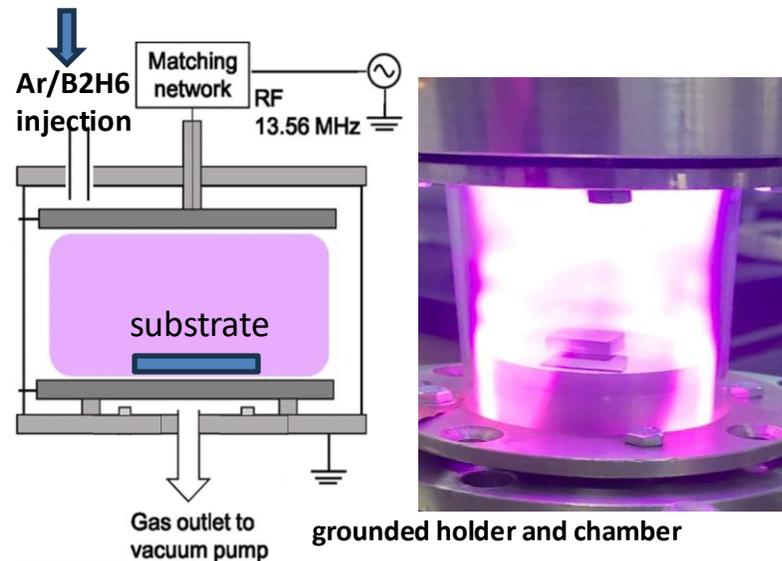
# Two PECVD configurations used for boron deposition

## Glow discharge (GD) configuration

Set-up glass tube+ 2 parallel plate electrodes (50 mm and distance in between electrode 60 mm

**Carrier gas: Ar and Precursor: H<sub>2</sub>/B<sub>2</sub>H<sub>6</sub>**

Variable parameters: RF power, Flow rates, pressure, deposition time, Substrate: Si, W



## RF plasma jet (J) configuration

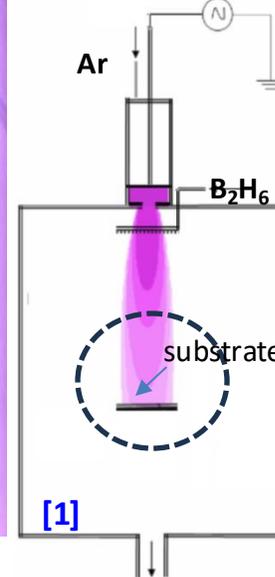
Set-up steel vessel +Jet plasma source used before for PECVD of nanostructure carbon

**Carrier gas: Ar and Precursor: H<sub>2</sub>/B<sub>2</sub>H<sub>6</sub>**

Variable Working parameters:

RF power, Nozzle substrate distance, flow rates , Pressure, Deposition time, Temperature, Substrate: Si, W

Images of the plasma jet in Ar / B<sub>2</sub>H<sub>6</sub>



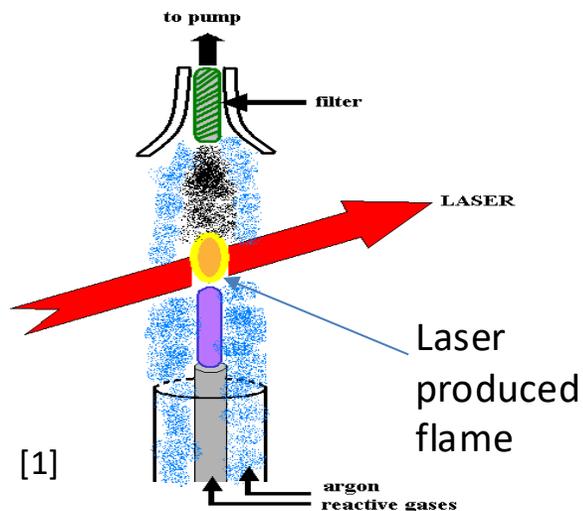
Gas ratio: Ar/Diborane

1000/5 (sccm)

300/5 (sccm)

[1]. S. Vizireanu et al, Plasma Sources Science & Technology 19, 034016, 2010.

# Laser pyrolysis used for Boron based nanoparticles



**Experimental method: laser pyrolysis**  
 $B_2H_6$  was used as B precursors

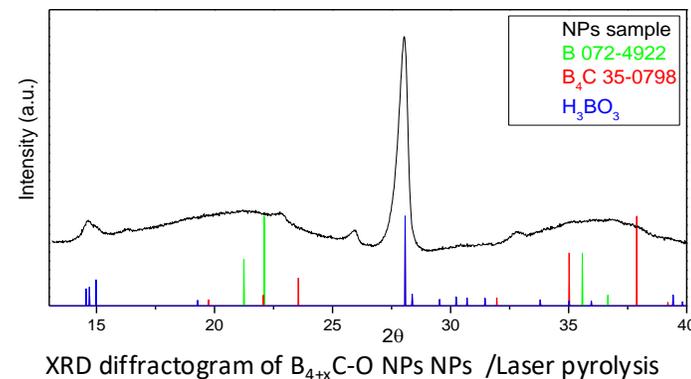
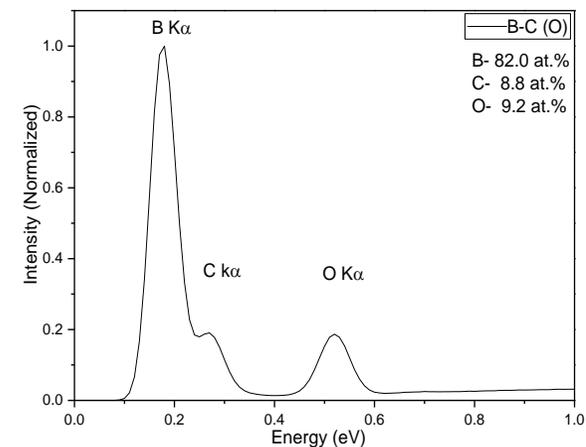
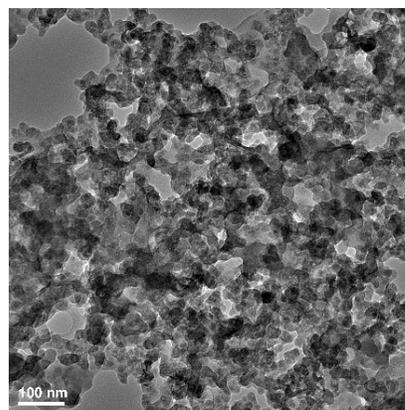
## Advantages:

- ✓ pure and reproducible nano-products
- ✓ extremely fine and monodisperse powders ( $d < 30$  nm);
- ✓ continuous synthesis **with high rate ~1-10 g/h;**
- ✓ **B doped materials, B carbide and nitride: (Fe,Ti, Si) borides.**

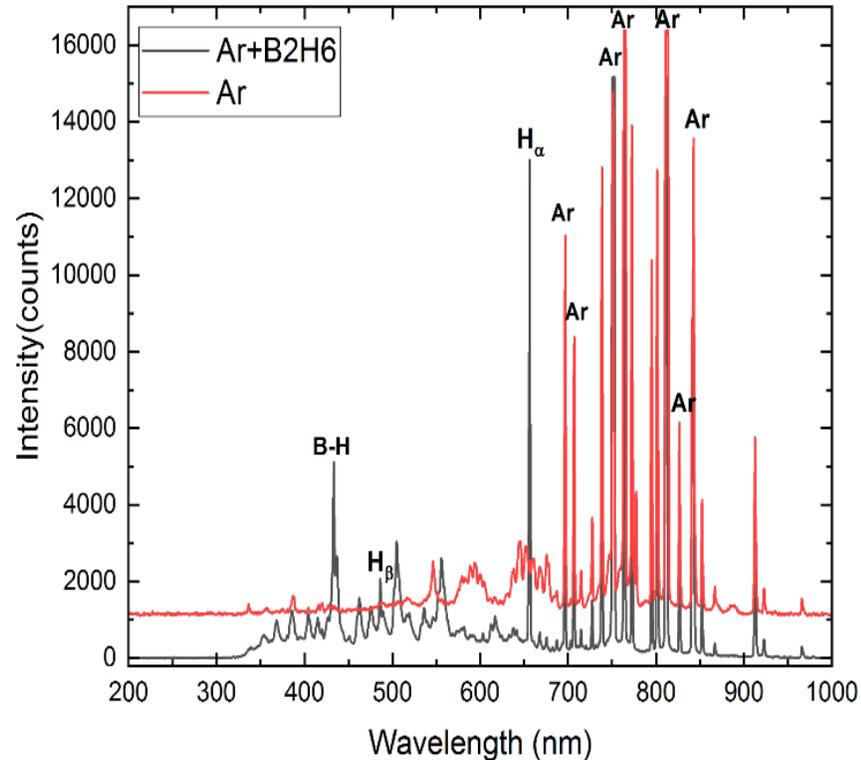
[1]. Balas M.; Dumitrache F. et al, Nanomaterials 2018, 8, 495 <https://doi.org/10.3390/nano8070495>

Specific synthesis of Boron rich NPs: B-C (O) NPs

Reactive mixture:  $B_2H_6 / C_2H_2 / C_2H_4$ : 8/1/3 (sccm),  $T_{flame} = 780$  °C

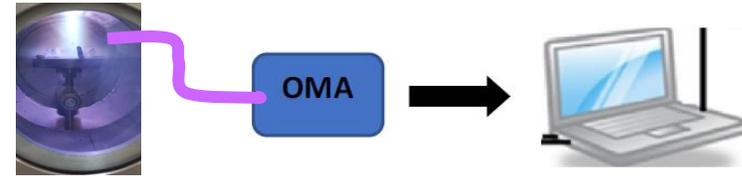


# Preliminary Ar/B<sub>2</sub>H<sub>6</sub> plasma jet investigation



OES in plasma jet of Ar/diborane mixture

Plasma jet Ar/ B<sub>2</sub>H<sub>6</sub> at 1000/5



Plasma +Optical fiber+ Optical multichannel analyzer+ acquisition

**OES investigations** show the presence the Argon lines, and BH bands, H<sub>α</sub> and H<sub>β</sub> lines in plasma jet after introduction of 5 sccm of diborane.

**Further investigations:** Detailed studies follow after

I will mount a quartz window.

-**OES study** of He or D<sub>2</sub>/diborane plasma in various condition.

-**OES study** of boron films in interaction with plasma.

-**Mass spectrometry study of boron** films in interaction with plasma.  
Study of species during sputtering of boron layers in **D<sub>2</sub>/H<sub>2</sub> plasma**

# Experimental parameters and samples labels



## Labelling of samples:

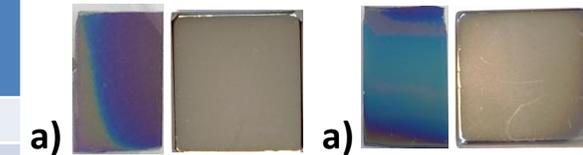
**H-samples** at High Ar flow (1000 sccm)+5sccm B<sub>2</sub>H<sub>6</sub>

**L-samples** at Low Ar flow (300 sccm) +5sccm B<sub>2</sub>H<sub>6</sub>

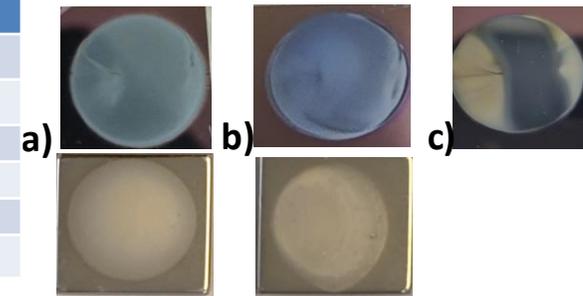
Samples label	Ar [sccm]	B <sub>2</sub> H <sub>6</sub> [sccm]	Deposition press. [mbar]	Time [min.]	Temper. Degree C
<b>1. Set I- Samples deposits by Glow Discharge (GD-samples)</b>					
GD-H	1000	5	0.7	10	
GD-L	300	5	0.4	10	
<b>2 Set II Samples deposits by plasma Jet (J-samples)</b>					
J-H	1000	5	0.7	10	
J-L	300	5	0.4	10	
J-H-RT	1000	5	0.73	10	47 °C
J-H-400C	1000	5	0.72	10	400 °C
J-H-600C	1000	5	0.71	10	600 °C
J-H-700C	1000	5	0.71	10	700 °C

a)

There are fixed parameters like RF power 100W, precursors kept always at the same flow values diborane: H<sub>2</sub>/B<sub>2</sub>H<sub>6</sub> = 5 sccm



Pictures of samples a) GD-H and b) GD-L on Si and W substrates



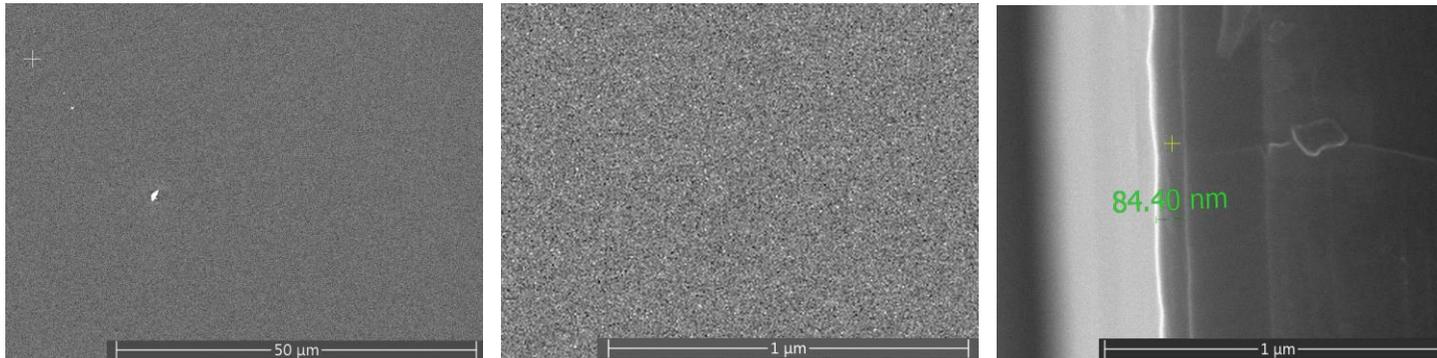
Pictures of samples a) J-H; b) J-L and c) J-H-RT to an intermediate Ar flow (500 sccm)

# Glow discharge GD-samples: Surface morphology



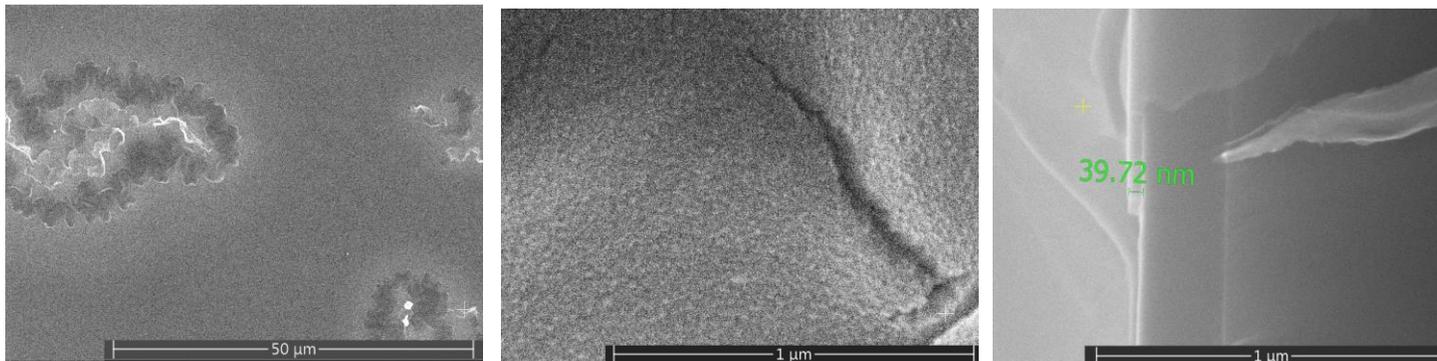
SEM investigation results: top view and cross sections

Time: 10 minutes, thickness ~84 nm



Smooth films  
Deposit. rate: **8.4 nm/min**

**GD-H** on Si in **Ar/B<sub>2</sub>H<sub>6</sub>** ratio 1000/5 sccm top and cross section

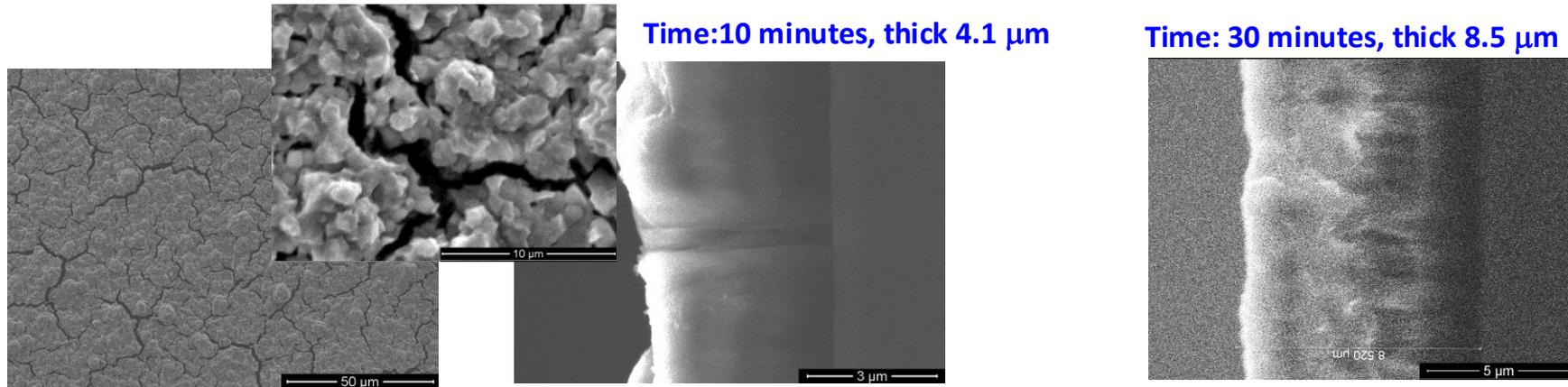


Smooth films  
Deposit. rate: **4 nm/min**

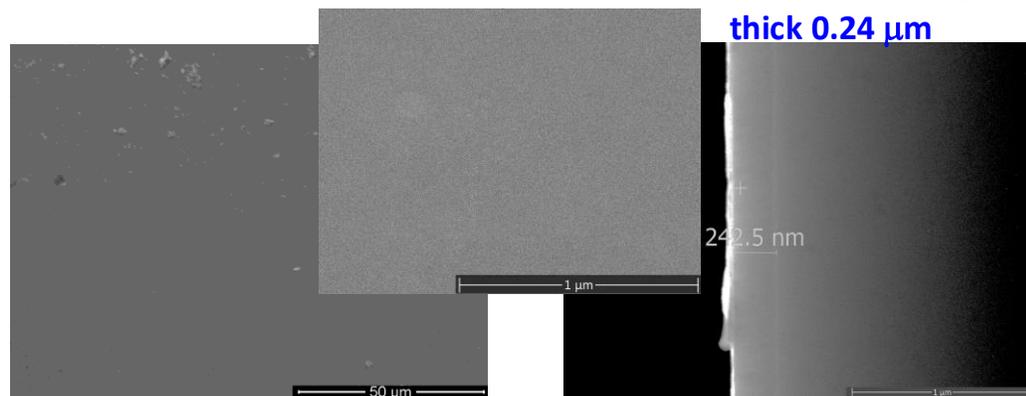
**GD-L**, on Si from **Ar/B<sub>2</sub>H<sub>6</sub>** ratio 300/5 sccm- Thickness: **40 nm**



# Plasma jet (J) samples: Surface morphology

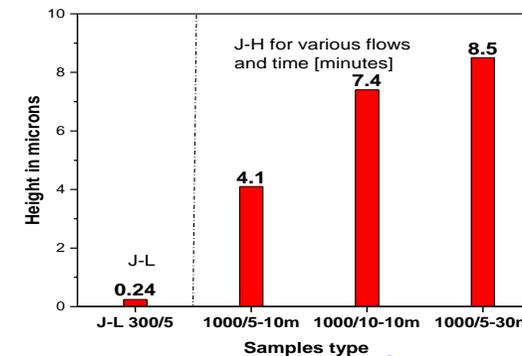


SEM images of J-H 1000/5 sccm top and cross section. **J-H samples are rough.**



SEM images of J-L samples 300/5 sccm J-L samples are smooth and small **deposition rate ~24 nm/min**

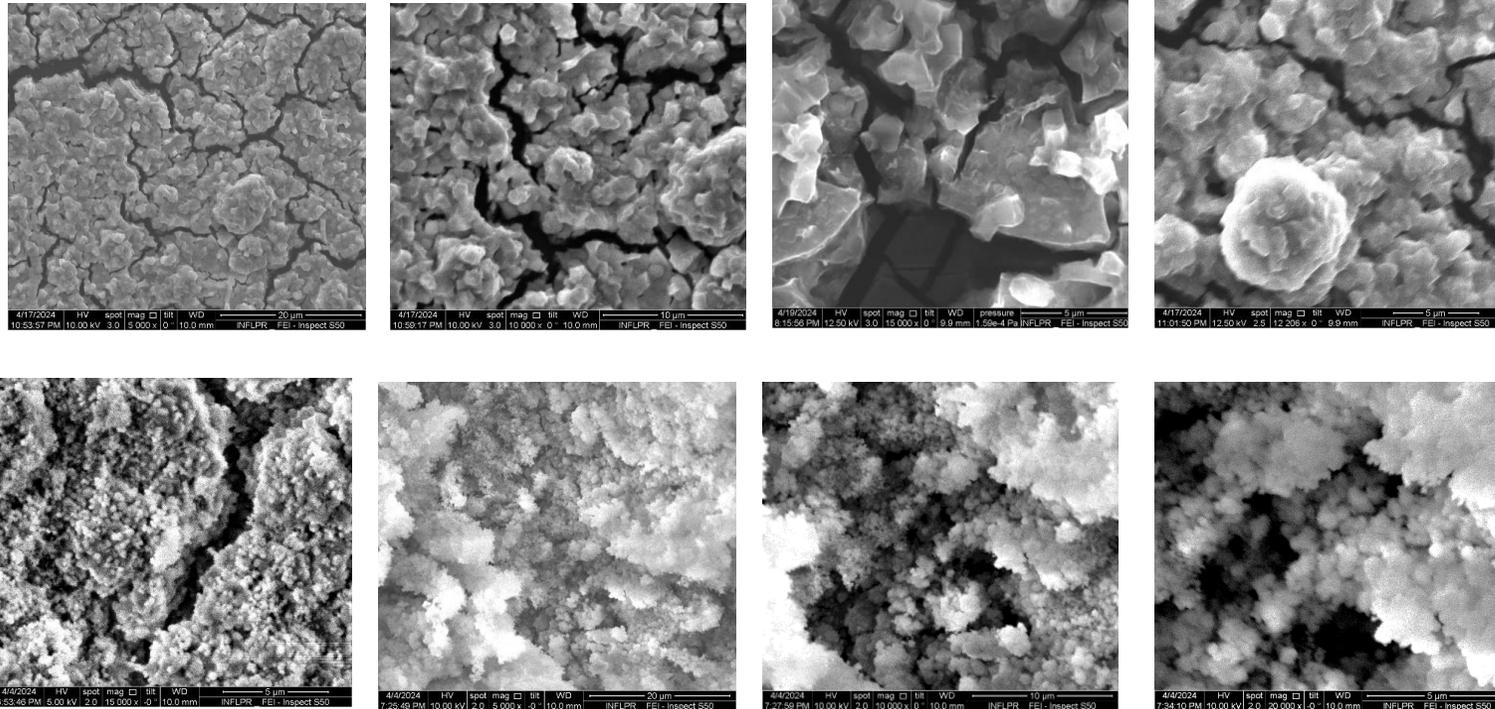
Deposition rate of J-H samples at about 400 nm/min



# J-H samples. Details on morphology



case of J-H: for high Ar flows, the sample are very rough and irregular



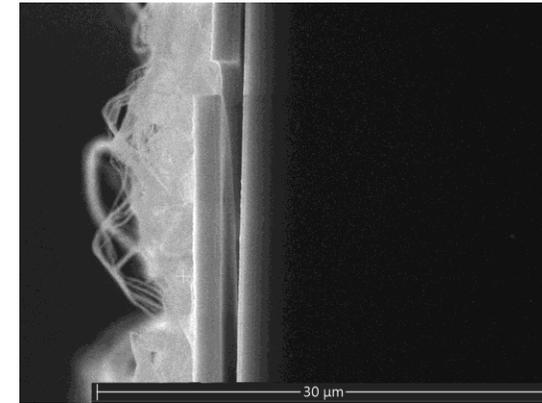
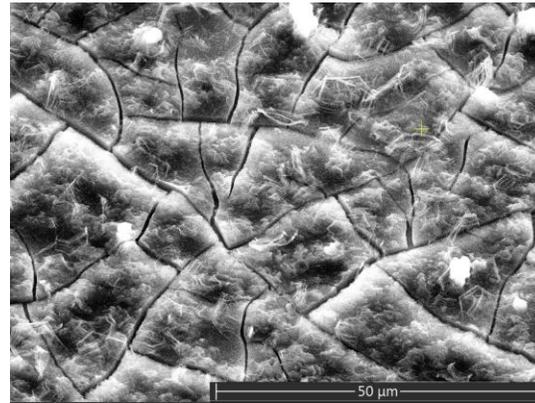
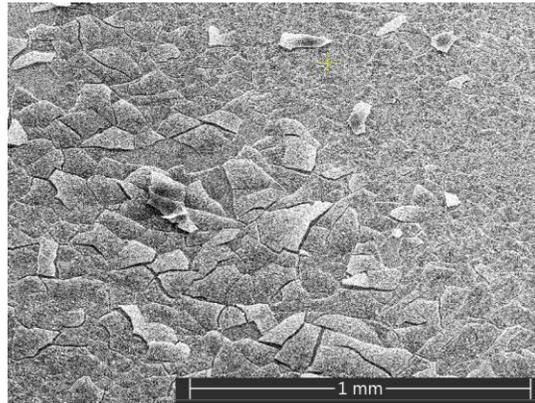
**Thick layer present many cracks and sponge-like morphology**  
**At the film edges, a whitish color is observed, the film are oxidized and nanoparticles appear**

# Time stability: J-H sample on substrates Si



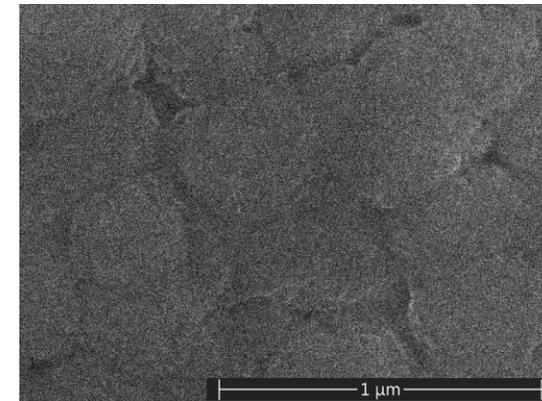
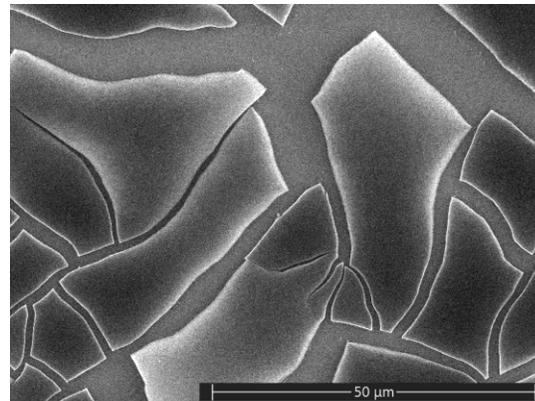
Adhesion behaviour in time (after 6 months)  
of thick film deposited at (Ar/B<sub>2</sub>H<sub>6</sub> 1000/10 sccm)

Initial  
SEM



SEM images of J-H sample  
after 6 month.

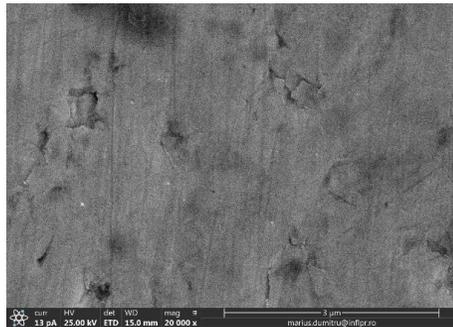
Boron films are  
delaminated Exfoliation of  
thick layer can be  
observed after 6 months



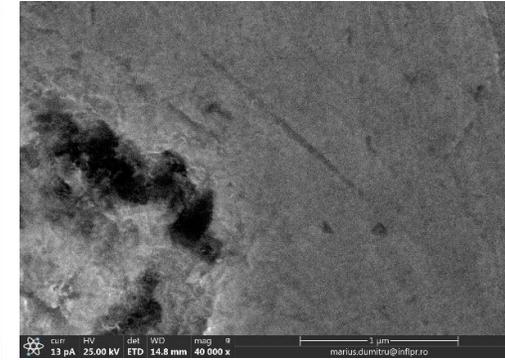
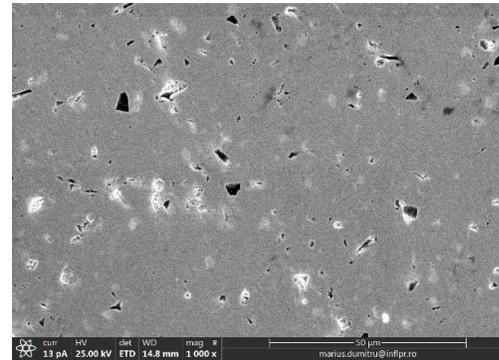


# Boron-GD samples on W substrates

SEM image GD boron films onto W substrate- measured after 6 month

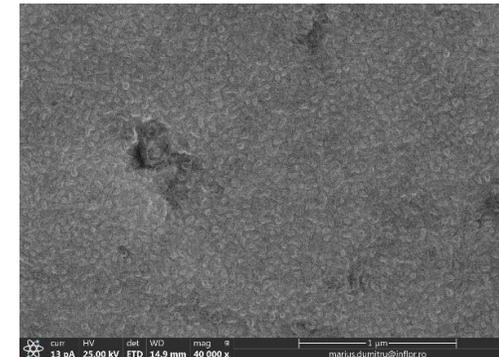
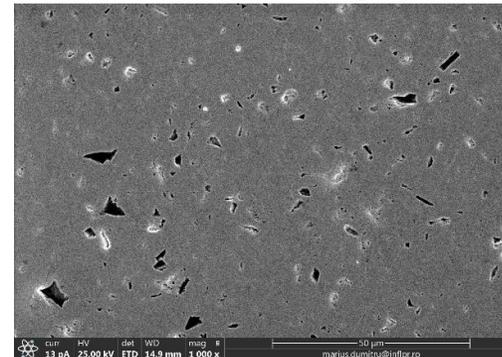


SEM image of the polished W substrate



Conformal film

GD-H on W in Ar/B<sub>2</sub>H<sub>6</sub> at 1000/5 layers (about 84 nm onto Si) :



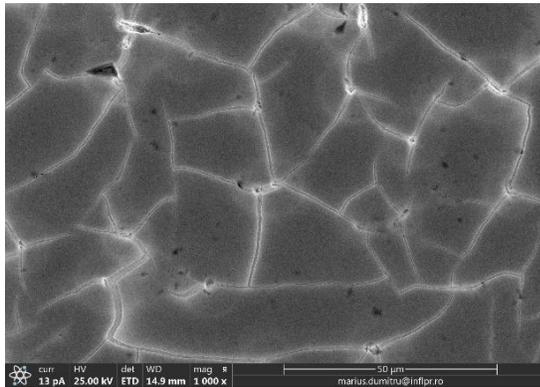
No delamination are observed

GD-L on W in Ar/B<sub>2</sub>H<sub>6</sub> at 200/5 (layers of about 40 nm onto Si)

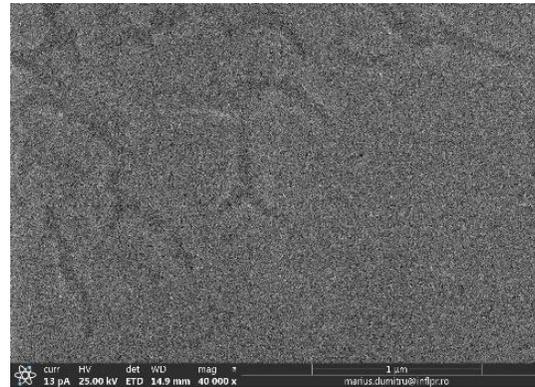


# Boron-J samples on W substrates

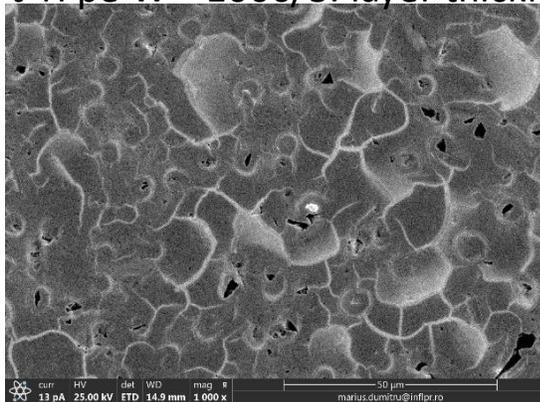
SEM image Jet boron films onto W substrate- measured after 6 months



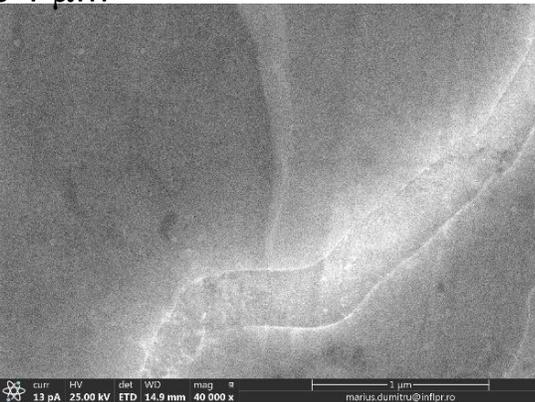
J-H pe W 1000/5: layer thickness 4 μm



→ cracks in the film are observed, however the layer does not completely delaminate



J-L on W 300/5: layer thickness 240 nm

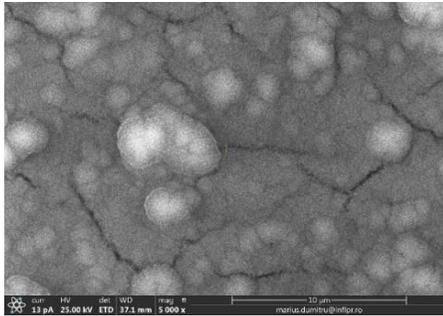


→ Delamination or flakes deposition?  
We have SEM only after 6 month for J-L on W

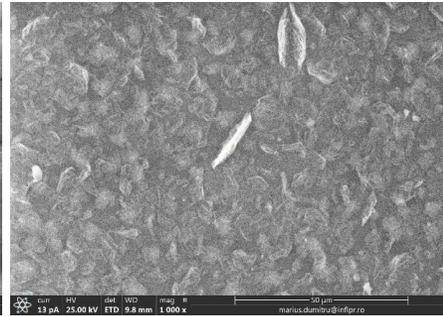
# Boron-J-H samples obtain for various temperatures



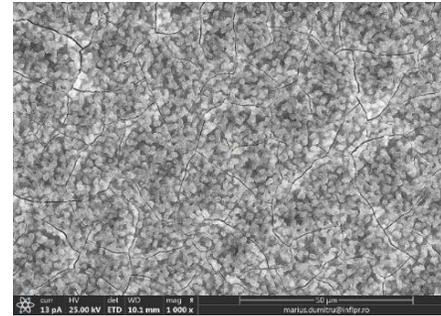
Room Temp.



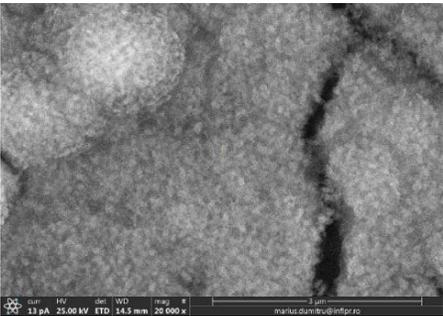
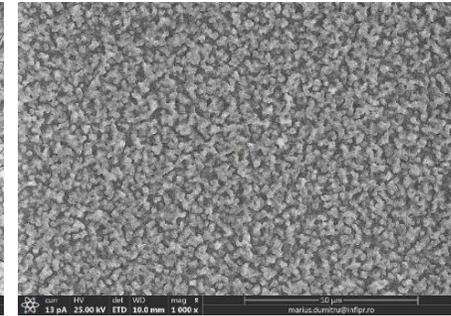
400 C



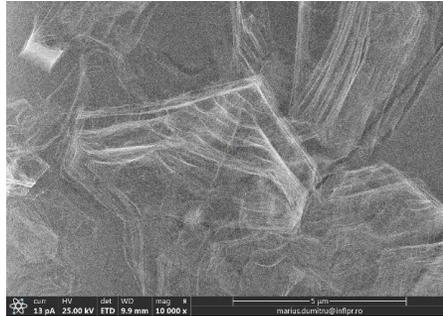
600 C



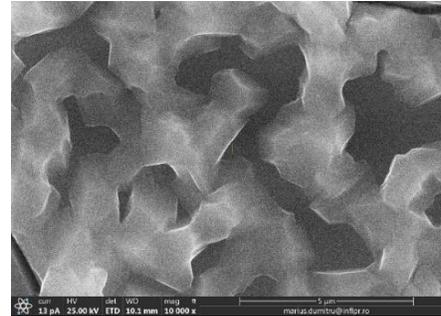
700 C



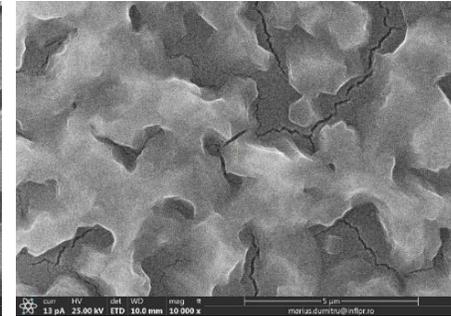
Room Temp.



400 C



600 C



700 C

SEM images of J-H (Ar/B<sub>2</sub>H<sub>6</sub> at ratio 1000/5 sccm, 100 W for 10 minutes at various temperatures.

The boron films are nanostructured at high temperatures. Nano-flakes and nanotubes are observed after 400 C and sponge like nano-structures are visible at 600 and 700 C.

# XPS investigation- survey spectra and elemental composition

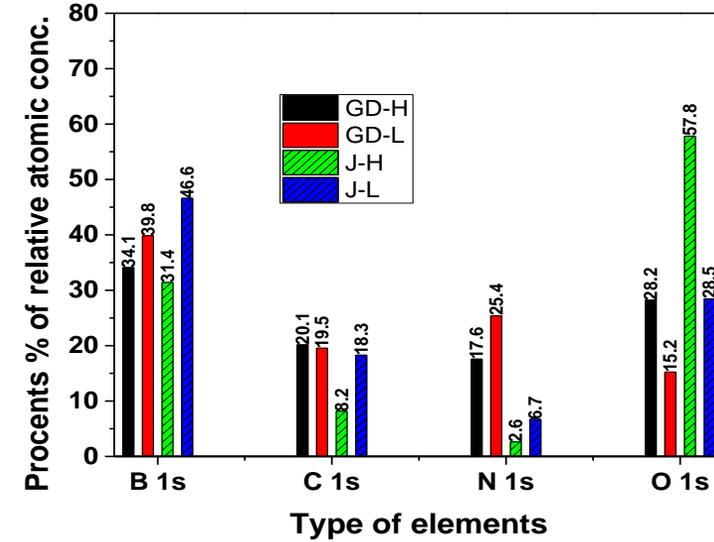
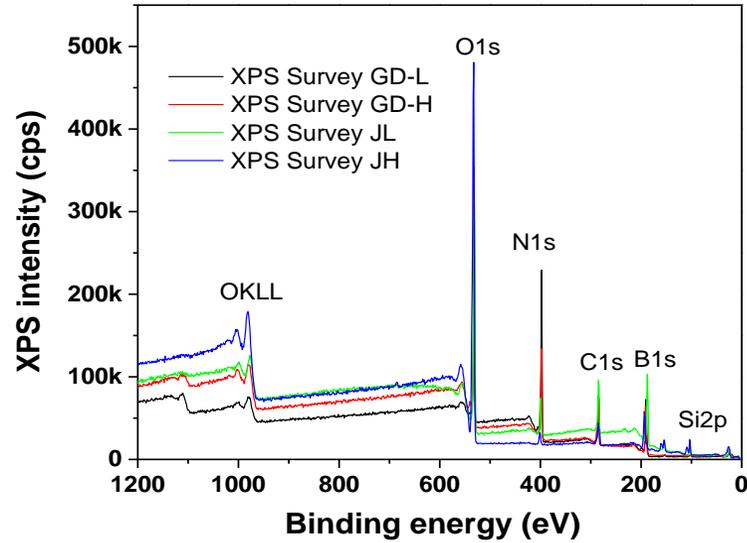
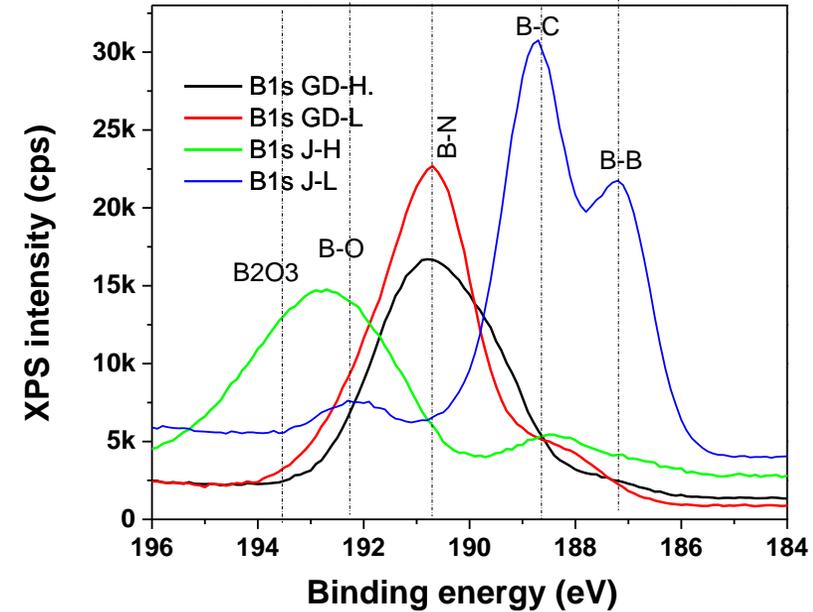
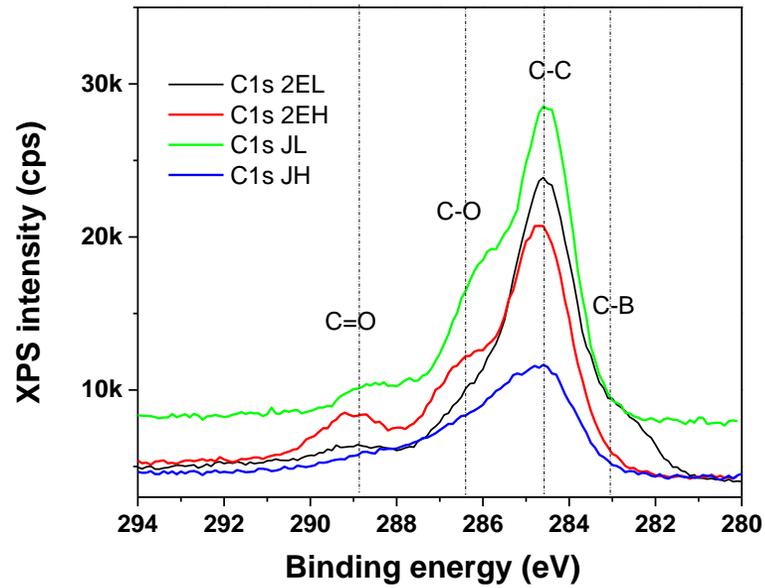


Table with relative atomic concentration of elements in the samples

	GD-H	GD-L	J-H	J-L
B 1s	34.1	39.8	31.4	46.6
C 1s	20.1	19.5	8.2	18.3
N 1s	17.6	25.4	2.6	6.7
O 1s	28.2	15.2	57.8	28.5

- Boron, carbon, nitrogen and oxygen elements;
- **Boron is dominant element;**
- High Ar flow rate led to a smaller B content and samples oxidation compared to L-rate;
- Lower Nitrogen and Carbon content in Jets sample;
- Oxides and nitride from air leaks and exposure.

# XPS investigation- High resolution in C1s and B1s regions and bonding types

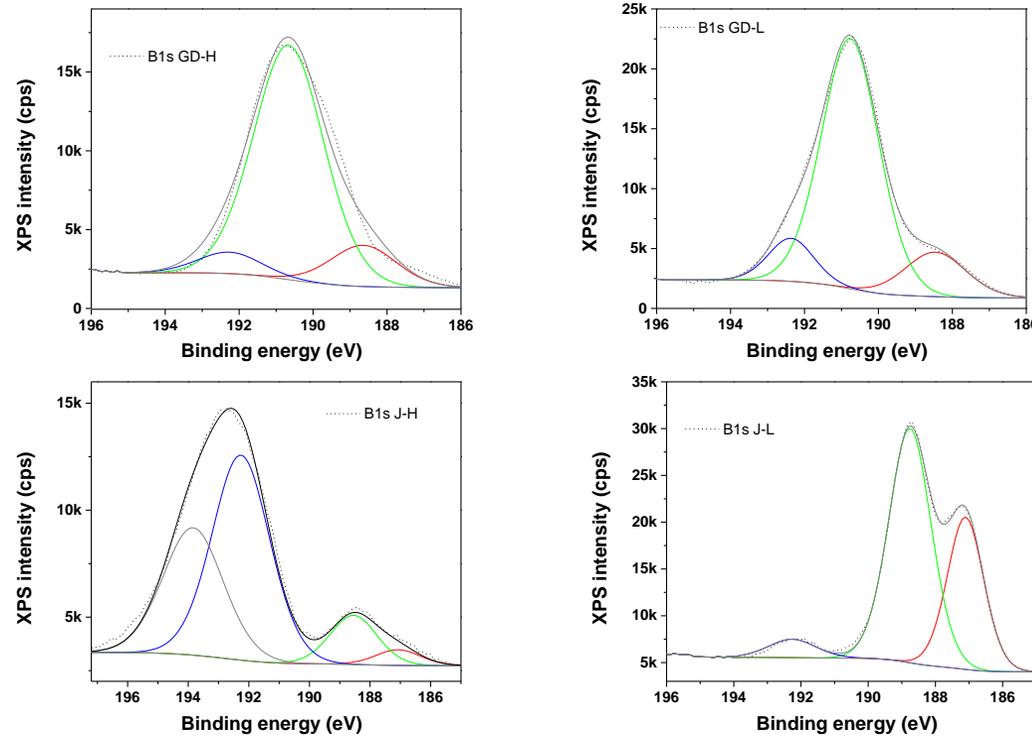


## High resolution XPS spectra in the C1s and B1s region.

After calibration to C1s peak we observed various bond type of Carbon and Born atoms in the PECVD sample.



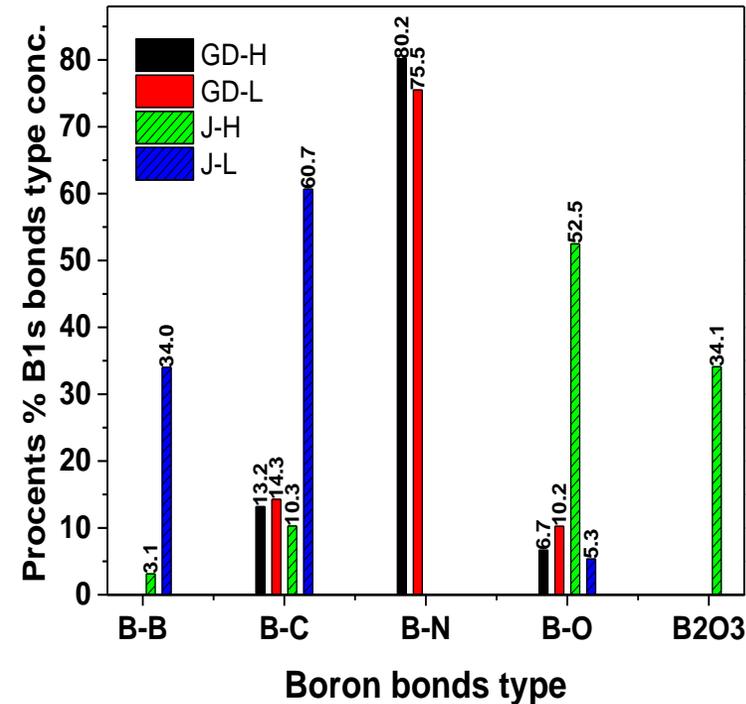
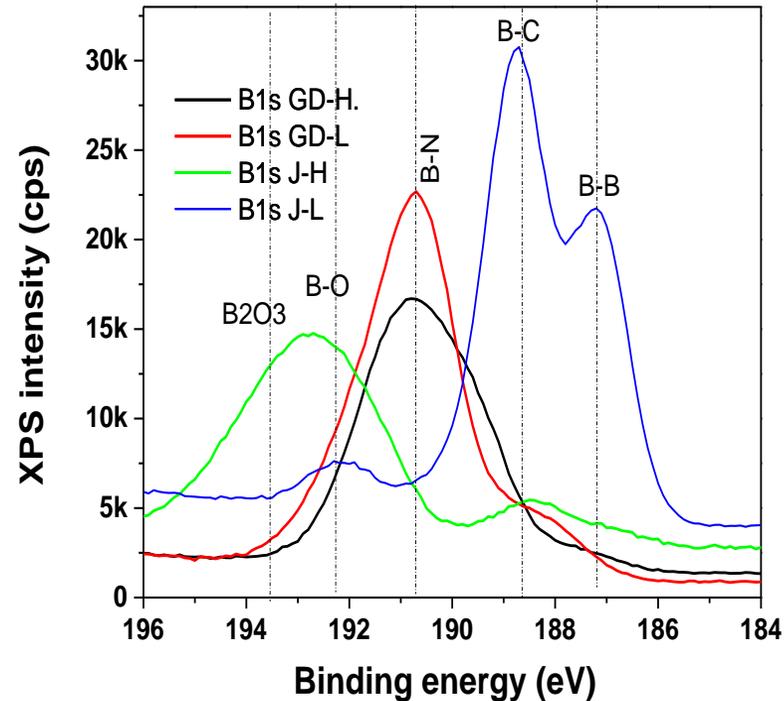
# Boron bonds type - B1s region deconvolution



Bond type	Binding en.[eV]
(B-B),	187.2 ±0.1
(B-C);	188.5±0.1
(B-N),	190.8±0.1
(B-O subox.)	192.4±0.1
B <sub>2</sub> O <sub>3</sub>	193.5±0.1

Deconvolution of high resolution XPS spectra in B1s region (binding energies found in the literature)

# XPS investigation- High resolution in B1s regions and bonding types and their percentage



High resolution XPS spectra in the B1s region

Diagram with percentages of B1s components

J-L contain metallic boron and J-H shows the most oxidized boron.

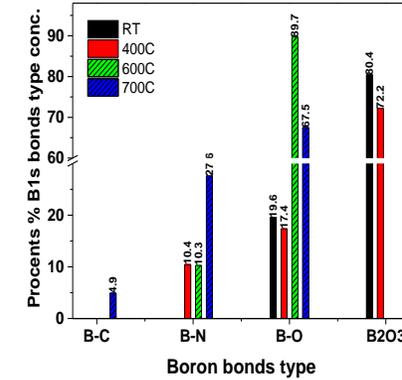
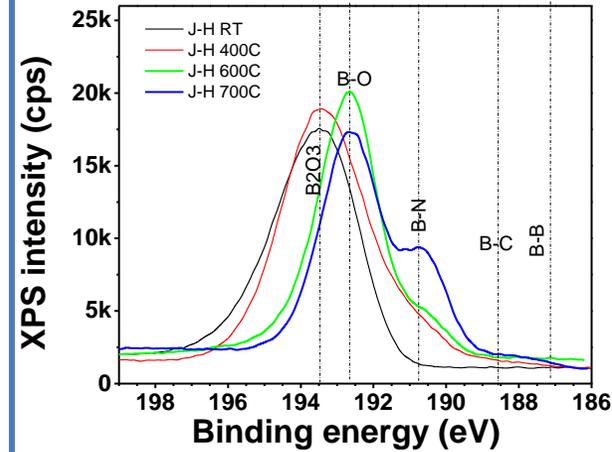
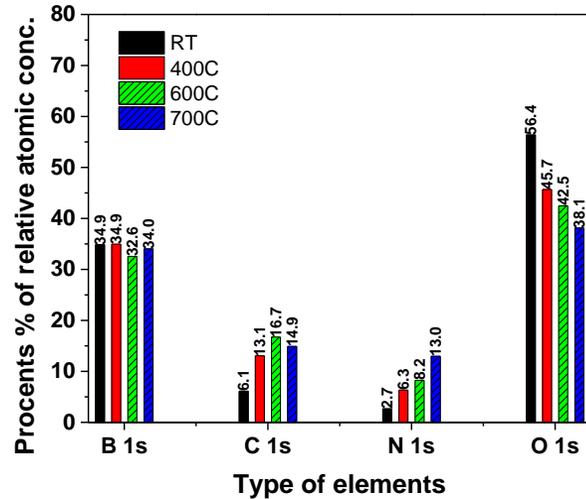
GD samples presents boron nitride bond type because of poor vacuum - mechanical pumps.

# Composition of boron PECVD samples for various temperatures



Table with elemental composition from survey spectra for boron at various temperature

	RT	400C	600C	700C
B 1s	34.9	34.9	32.6	34.0
C 1s	6.1	13.1	16.7	14.9
N 1s	2.7	6.3	8.2	13.0
O 1s	56.4	45.7	42.5	38.1



High resolution XPS spectra in the B1s region of samples deposited at various temperature. **Samples present oxidized boron.**

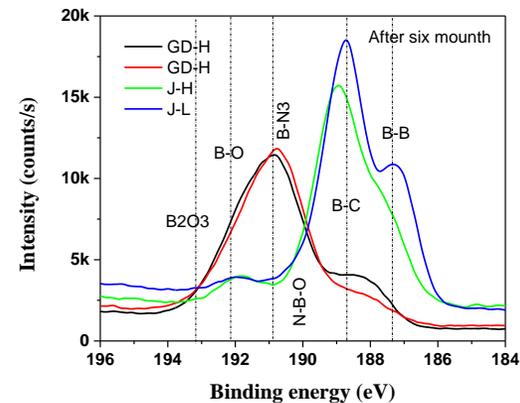
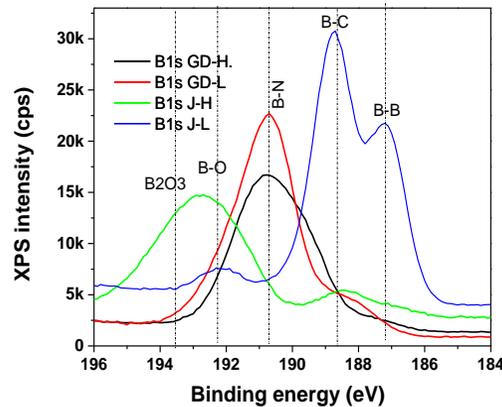
# Time stability of composition in time

(after 6 months, substrates Si)



Table with elemental composition of initial and after 6 months of boron samples obtained by GD and plasma Jet

	GD-H	+6 m	GD-L	+6 m	J-H	+6 m	J-L	+6 m
B 1s	<b>34.1</b>	<u>34.0</u>	<b>39.8</b>	<u>31.8</u>	<b>31.4</b>	<u>31.1</u>	<b>46.6</b>	<u>39.8</u>
C 1s	<b>20.1</b>	27.2	<b>19.5</b>	28.6	<b>8.2</b>	26.4	<b>18.3</b>	30.9
N 1s	<b>17.6</b>	19.7	<b>25.4</b>	18.7	<b>2.6</b>	7.4	<b>6.7</b>	6.3
O 1s	<b>28.2</b>	19.1	<b>15.2</b>	21.0	<b>57.8</b>	35.1	<b>28.5</b>	23.0



**High resolution XPS spectra in the B1s region of boron PECVD samples measure after days and 6 months.**

We can observed variation in B, C, N and O concentration.

The GD samples that presents **boron nitride bonds** are quite stable because are difficult to oxidize over time.

In the J-L samples that contain B-B and B-C remains almost the same shape.



# Conclusions

- We demonstrated that we can obtain boron layers by PECVD in Ar/B<sub>2</sub>H<sub>6</sub> mixture;
- High deposition rate for **jet** (~400 nm/min) and low rate for **glow discharge** (4-8 nm/min);
- Good adhesion of the thin B layers on W surface, and low adhesion on Si wafers;
- For thin boron film the morphology remains stable in time (both GD-L and J-L at Low Ar);
- The boron films **are nanostructured at high temperatures**;
- The composition of boron layers deposited by PECVD from diborane contains in various concentrations B, C, N and O elements.
- In the **Jets** samples we have **metallic boron and oxide bonds type**, while in the **GD** samples we found mostly **boron nitride bonds type**. The boron bonds type seems to be preserved after 6 months, except J-H samples which are quite spongy (not compact);
- Modification of the composition of boron layers are observed in time.



# Future plans

## Infrastructure:

- Improving the work safety by inserting higher sensitivity diborane detectors, new system for burning the pumps exhaust;
- Optimization of the deposition setups ( high vacuum pumping systems, mass flow controllers, diborane bottles – also with He, or D<sub>2</sub>, quartz windows for OES);
- Development of new diborane discharge configurations relevant for fusion (we have know-how in designing of new plasma sources with injection for PECVD).

## Research

- Study of the boronization process (efficiency, species formed, influence of impurities) using diborane or other boron containing precursors by PECVD. Use diagnostics and characterization techniques for:
  - Species formed during sputtering of boron layers in D<sub>2</sub>/H<sub>2</sub> plasma (Optical emission spectroscopy and mass spectrometry available);
  - Properties of Boron films deposited by PECVD using diborane (morphology, composition, adhesion, hardness, resilience to sputtering etc).
- Identification of the critical issues in boronization, of interest for fusion technology: process, adhesion, time stability, behaviour in respect to sputtering;
- Identification of the needs for PECVD preparation of thick/thin Boron layers for materials study (substrate types, pre-treatment, thickness, etc ).